

S/N 09/901001

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Kie Y. Ahn et al.	Examiner:	Kathleen Duda
Serial No.:	09/901001	Group Art Unit:	1756
Filed:	July 09, 2001	Docket:	1303.016US1
Title:	COPPER ELECTROLESS DEPOSITION TECHNOLOGY FOR ULSI METALIZATION		

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TCL 1700INFORMATION DISCLOSURE STATEMENT

MS RCE
Commissioner for Patents
P.O. Box 1450
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In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. § 1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement.

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

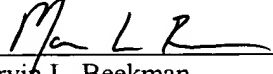
Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

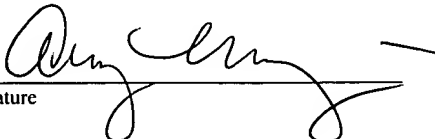
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Date 11-21-03

By 
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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop RCE, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 21st day of November, 2003.

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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**
(Use as many sheets as necessary)



Complete if Known

Application Number	09/901001
Filing Date	July 9, 2001
First Named Inventor	Ahn, Kie
Group Art Unit	1756
Examiner Name	Duda, Kathleen

Sheet 1 of 1

Attorney Docket No: 1303.016US1

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US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
	US-010002333	05/31/2001	Huang, Chao-Yuan , et al.	438	637	03/29/1999
	US-5,814,557	09/29/1998	Venkatraman, Ramnath , et al.	438	622	05/20/1996
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	US-5,940,733	08/17/1999	Beinglass, Israel , et al.	438	655	07/29/1997
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	US-6,429,120	08/06/2002	Ahn, Kie Y., et al.	438	635	01/18/2000

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
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OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		"SiLK* D SEMICONDUCTOR DIELECTRIC RESIN", <u>The DOW Chemical Company, www.silk.dow.com, (Unknown),2</u>	
		"SiLK* J SEMICONDUCTOR DIELECTRIC RESIN", <u>The DOW Company, www.silk.dow.com, (unknown),2</u>	
		EISENBRAUN, E. T., et al., "Selective and Blanket Low-Temperature Copper CVD for Multilevel Metallization in ULSI", <u>Conference Proceedings ULSI-VII, (1992),5 pages</u>	
		KALOYEROS, A. E., et al., "Blanket and Selective Copper CVD from Cu(FOD)2 for Multilvel Metallization", <u>Mat. Res. Soc. Symp. Proc., Vol. 181,(1990),6 pages</u>	
		MARTIN, STEVEN J., "THE INVENTION AND DEVELOPMENT OF A LOW-DIELECTRIC CONSTANT POLYMER FOR THE FABRICATION OF INTEGRATED CIRCUIT INTERCONNECT", <u>Seminar Department of Chemical Engineering, North Carolina State University, (April 9, 2001),1</u>	
		ZHANG, F , et al., "Nanoglass TM E Copper Damascene Processing for Etch, Clean, and CMP", <u>www.electronicmaterials.com/star_center/technical_papers.html, (2001),6</u>	

EXAMINER

DATE CONSIDERED

Substitute Disclosure Statement Form (PTO-1446)

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. 1 Applicant's unique citation designation number (optional) 2 Applicant is to place a check mark here if English language Translation is attached